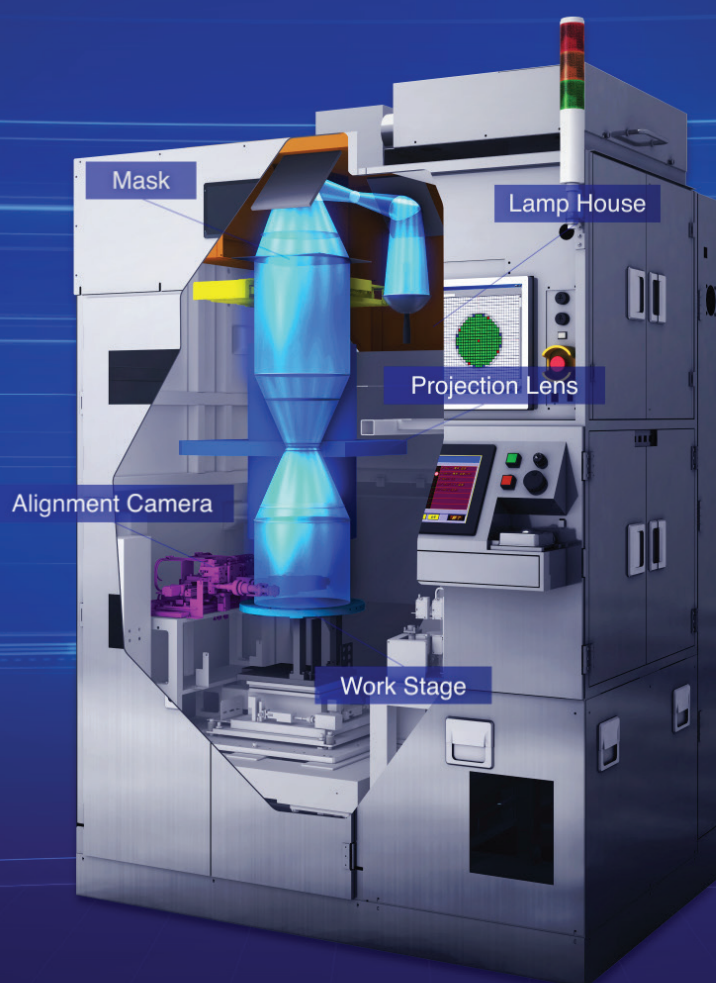


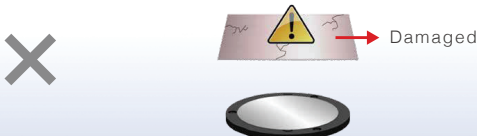
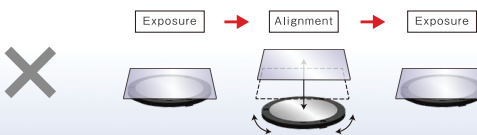
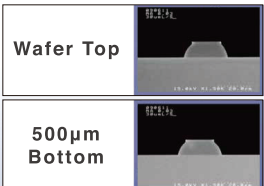
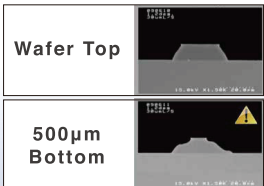
UX-4

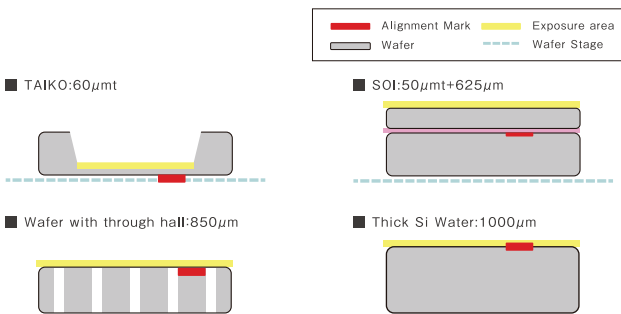
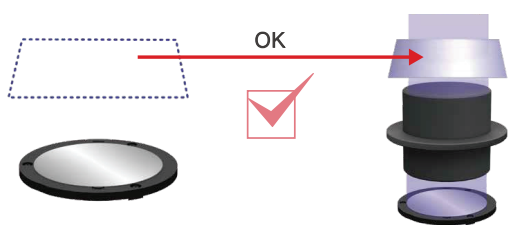
Full-Field Projection Aligner



Resolution	2 μ m L/S~
Overlay	Top Side : $\pm 1\mu$ m, Back Side : $\pm 1.5\mu$ m
Throughput	120wph
Wafer Size	$\Phi 100$ mm / 150mm / 200mm
	Si, Sapphire, GaN, GaAs,
Wafer Transfer	Cassette to Cassette Automatic

Advantage of Full-Field Projection Lithography

	UX-4(Full-Field Projection)	Proximity/Contact Aligner
Mask Damage Free	 No mask-wafer contact throughout the process.	 Damaged
High Productivity	 Full-Field Projection > Proximity/Contact Aligner	
3D Lithography	 Large Depth of Focus. High resolution on both top and bottom of step.	
Thick Resist Process	 No mask-wafer sticking problem with thick-sticky resist.	 Stuck

Flexibility on wafer format	Mask Compatibility
	 OK Use your own contact aligner mask. No special mask needed.



USHIO EUROPE B.V. - Headquarters
The Netherlands | +31 20 446 9333
sales@ushio.eu | www.ushio.eu

USHIO GERMANY GmbH
Germany | +49 8094 906 0
sales@ushio.de | www.ushio.de

USHIO U.K., LTD.
United Kingdom | +44 129 625 6067
sales@ushio.eu | www.ushio.eu

USHIO FRANCE S.A.R.L.
France | +33 134 64 94 94
sales@ushio.eu | www.ushio.eu